









Release Date: 28 February 2014 Version: A1.0

PRODUCT DATASHEET



- ► PLCC2
- ➤ 3020 Series
- ► Green (525nm)

N0G07S06











3020 Series

APPLICATIONS:

- Backlighting
- Indicator
- Switch Lighting
- **Decoration Lighting**
- Light Bar

FEATURES:

- Package: PLCC White SMT Package
- Forward Current: 150mA Forward Voltage (typ.): 3.2V
- Luminous Flux (typ.): 9000mcd @150mA
- Colour: Green Wavelength: 525nm Viewing angle: 120°
- **Materials:**
 - Die: InGaN
- Resin: Silicon (Water Clear) Operating Temperature: -20~+80°C
- Storage Temperature: -30~+100°C
- **ESD:** 500V
- **Grouping parameters:**
 - Forward voltage
 - Luminous flux
 - Wavelength
- Soldering methods: IR Reflow soldering Preconditioning: acc. to JEDEC Level 3
- Packing: 8mm tape with 2000/reel, ø180mm (7")



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	150	mA
Peak Forward Current Duty 1/10@10KHz	I _{FP}	300	mA
Reverse Current @5V	I _R	10	μΑ
Power Dissipation	PD	570	mW
Electrostatic Discharge	ESD	500	V
Operating Temperature	T _{OPR}	-20~+80	°C
Storage Temperature	T _{STG}	-30~+100	°C

Electrical & Optical Characteristics (Ta=25°C)

Darameter	Symbol	Values		Unit	Test	
Parameter	Зуппон	Min.	Тур.	Max.	Onit	Condition
Forward Voltage	V_{F}	2.8		3.8	V	I _F =150mA
Luminous Intensity	I _V	6500	9000	10000	mcd	I _F =150mA
Dominant Wavelength	λ_{D}		525		nm	I _F =150mA
Spectral Line Half Bandwidth	Δλ		36		nm	I _F =150mA
Viewing Angle	2θ _{1/2}		120		deg	I _F =150mA

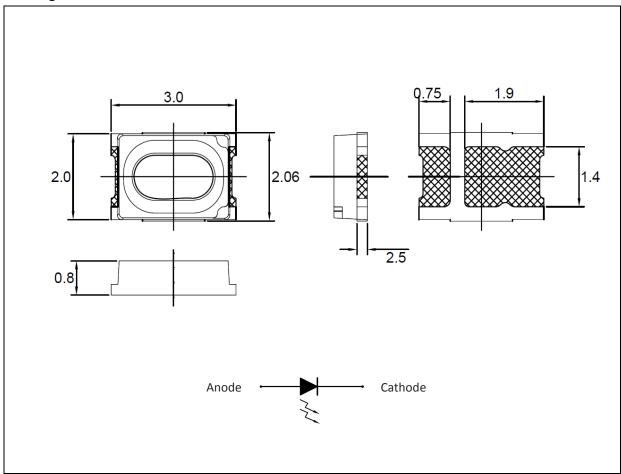
^{1.} Luminous intensity (Iv) $\pm 15\%$, Forward Voltage (VF) $\pm 0.1V$, Viewing angle($2\theta_{1/2}$) $\pm 5\%$, CRI ± 3

^{2.} IS standard testing



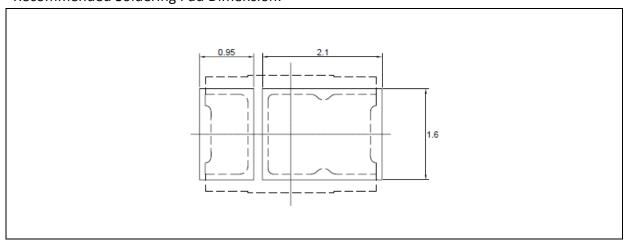
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm with angle tolerance ±0.5°.



BINNING GROUPS:

Forward Voltage Classifications ($I_F = 150 \text{mA}$):

Code	Min.	Max.	Unit
1	2.8	2.9	
2	2.9	3.0	
3	3.0	3.1	
4	3.1	3.2	
5	3.2	3.3	V
6	3.3	3.4	V
7	3.4	3.5	
8	3.5	3.6	
9	3.6	3.7	
10	3.7	3.8	

Luminous Flux Classifications ($I_F = 150 \text{mA}$):

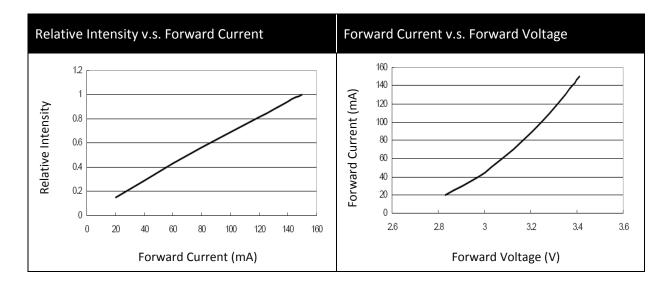
Code	Min.	Max.	Unit
AZ2	6500	8000	mad
AA1	8000	10000	mcd

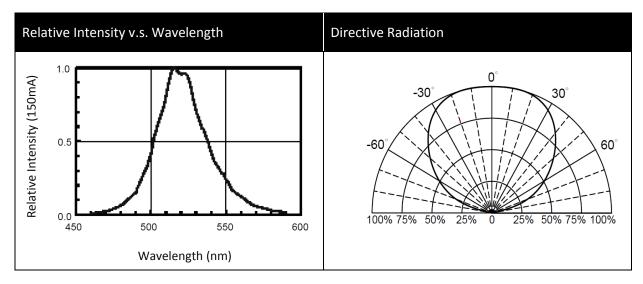
Dominant Wavelength Classifications ($I_F = 150 \text{mA}$):

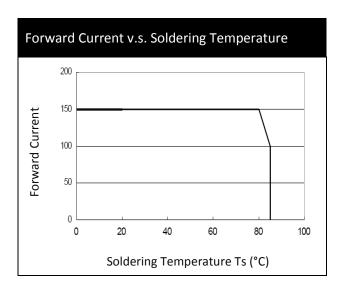
Code	Min.	Max.	Unit
10	519	522	
1P	522	525	nm
1Q	525	528	nm
1R	528	531	



ELECTRO-OPTICAL CHARACTERISTICS:



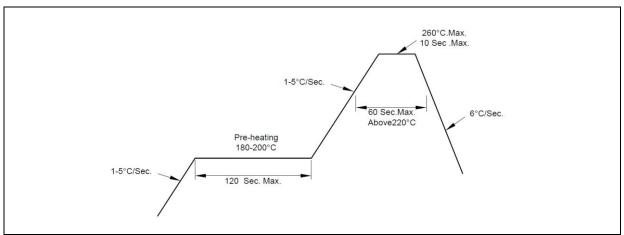






RECOMMENDED SOLDERING PROFILE:

Lead-free Solder:



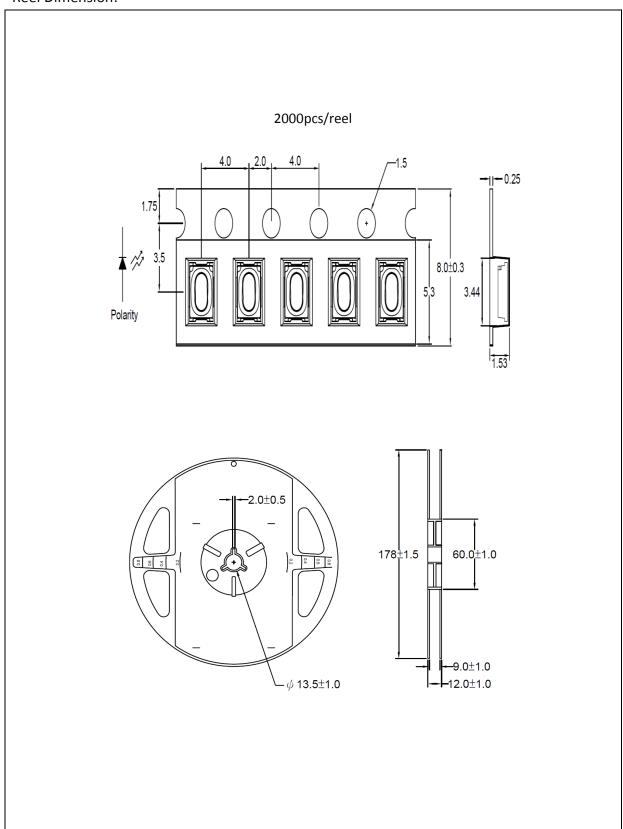
Note:

- 1. Maximum reflow soldering: 2 times.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking at 60°C±5°C for 15hrs before use.

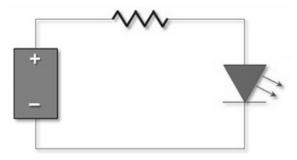
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 70±3°C x 24hrs and <5%RH, taped / reel package.
- 100±3°C x 2hrs, bulk (loose) package.
- 130±3°C x 30min, bulk (loose) package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	28/02/2014	Datasheet set-up.